

REMARKS

Reconsideration is respectfully requested.

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Claims 18-20 are pending. Claims 1-17 have previously been withdrawn.

Claims 18 and 20 stand rejected under 35 U.S.C. 102(b) as being anticipated by Wilson Woodruff (U.S. Patent Number 3,415,771). Furthermore, claim 18
10 and 19 stand rejected under 35 U.S.C. 102(b) as being anticipated by Van Brimer et al.

Claim 18 has been amended to state that the organic particles are fused together to form the undercoat and the undercoat is fused to the second surface
15 of the carrier. This has basis in the specification on page 11, lines 3-25.

Neither Wilson nor Van Brimer teach anything about fusing organic particles together both to form an undercoat and to adhere to the second surface of the carrier. In the case of Wilson, particles are mentioned but they are inorganic
20 particles that have no fusing properties (Wilson, column 4, lines 2-19). In the case of Van Brimer, the substantially transparent resinous support is actually laminated to the transparency with hot melt adhesive (Van Brimer, column 5 lines 33-54). Presently amended claim 18 and its dependent claims 19 and 20 are distinguishable over the cited art. The 102(b) rejections should be
25 withdrawn.

With the amendment to claim 18 described above, all the claims are in condition for allowance.


30 Applicants therefore request that the above rejections be withdrawn and that the present application be allowed.

Respectfully submitted,

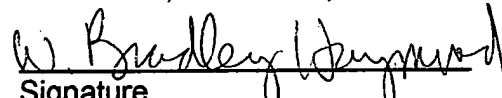
Kwasny et al.

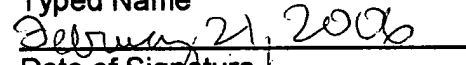
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